

(1.27 mm) .050"

RSM SERIES

SMT MICRO SOCKET

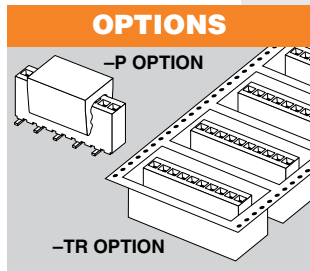
SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?RSM

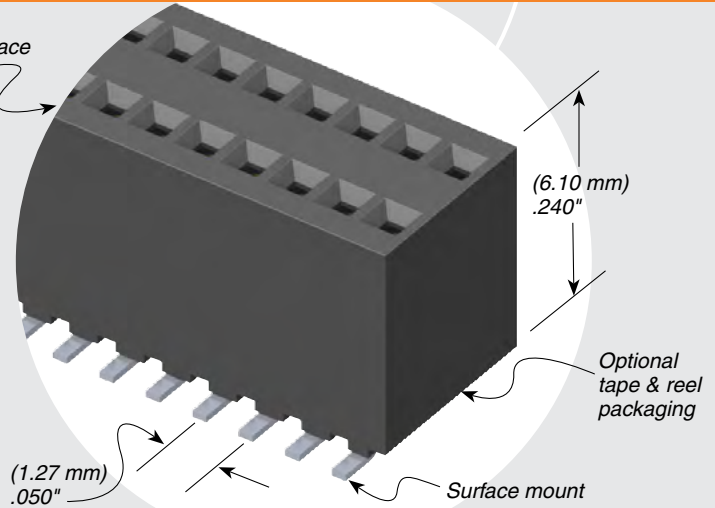
Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating (RSM/FTR):
3.1 A per pin
(1 pin powered per row)
Operating Temp Range:
-55 °C to +125 °C
Contact Resistance:
10 mΩ

Lead Size Accepted:
(0.46 mm) .018" SQ
Insertion Depth:
Top Entry = (2.64 mm) .104"
to (5.84 mm) .230" with
(0.38 mm) .015" wipe, or
pass-through.
Bottom Entry = (5.49 mm)
.216" minimum
(Add board thickness for
correct post OAL)
RoHS Compliant:
Yes

Mates with:
FTR, HTMS, HDWM,
DWM, TML, ZML, TMS



Optional
pick & place
pad



PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
 - Locking clips
- Contact Samtec.

RSM	1	NO. PINS PER ROW	02	PLATING OPTION	ROW OPTION	OPTION
02 thru 36				-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail	-S = Single Row -D = Double Row	-K = (6.25 mm) .246" DIA Polyimide film Pick & Place Pad (5 positions minimum for -D) (7 positions minimum for -S) -P = Plastic Pick & Place Pad (-D = 5 positions minimum -S = 6 positions minimum) -TR = Tape & Reel

Note: Some sizes, styles and options are non-standard, non-returnable.